

10-06-2003



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2388 U.S. PTO  
10/670532



09/26/03

To the Honorable Commissioner of Patents and Trademarks. Please record the attached original documents or copy thereof.

1. Name of Conveying Party(ies):

Additional names of conveying parties attached: ☐ Yes ☒ No

**YUTAKA OGAWA, KAZUTOMO OGURA,  
NAOFUMI SATOU AND KIYOTADA FUNANE**

2. Name and Address of Receiving Party(ies):

(1) Name: **Renesas Technology Corp.**

Address: 4-1, Marunouchi 2-chome

City: Chiyoda-ku, Tokyo, Japan

And

(2) Name: **Hitachi ULSI Systems Co., Ltd.**

Address: 22-1, Josuihoncho 5-chome

City: Kodaira-shi, Tokyo, Japan

3. Nature of Conveyance:

- ☒ Assignment ☐ Merger  
☐ Security Agreement ☐ Change of Name  
☐ Other:

Execution Date: **August 27, 2003**

4. (a) Patent Application Number(s):

If this document is being filed together with a new application,  
the execution date of the application is:

☐ Additional Numbers Attached.

4. (b) Patent Numbers:

5. Name and Address of Party to whom Correspondence  
Concerning this Document Should be Mailed:

Name: **Stanley P. Fisher**

Address: **Reed Smith LLP**  
3110 Fairview Park Dr.  
Suite 1400  
Falls Church, VA 22042

6. Total Number of Applications and Patents Involved: 1

7. Total Fee: **\$40.00**  
(37 C.F.R. § 3.41)

- ☒ Enclosed.  
☒ Authorized to be charged to deposit account.

8. Deposit Account Number: **08-1480**

ATTACH DUPLICATE COPY OF THIS PAGE IF PAYING BY DEPOSIT ACCOUNT

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9. Statement and Signature:

*To the best of my knowledge and belief, the foregoing is true and correct and any attached copy is a true copy of the original document.*

Stanley P. Fisher, Registration No. 24, 344

**September 26, 2003**  
Juan Carlos A. Marquez, Registration No. 34,072

Total number of pages comprising cover sheet: 1

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**ASSIGNMENT**  
( 譲 渡 証 )

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by   Renesas Technology Corp.,  
and   Hitachi ULSI Systems Co., Ltd.,  
corporations organized under the laws of Japan,  
located at    4-1, Marunouchi 2-chome, Chiyoda-ku, Tokyo, Japan,  
and 22-1, Josuihoncho 5-chome, Kodaira-shi, Tokyo, Japan,  
receipt of which is hereby acknowledged I do hereby sell and assign to said   Renesas Technology Corp.,  
and   Hitachi ULSI Systems Co., Ltd.,  
their successors and assigns, all my right, title and interest, in and for the United States of America, in and to

**SEMICONDUCTOR INTEGRATED CIRCUIT DEVICE**

invented by me (if only one is named below ) or us (if plural inventors are named below ) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said   Renesas Technology Corp., and   Hitachi ULSI Systems Co., Ltd.,  
their successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said  
Renesas Technology Corp.,    and   Hitachi ULSI Systems Co., Ltd.,

Signed on the date(s) indicated aside our signatures:

INVENTOR(S)  
(発明者フルネームサイン)

Date Signed  
(署名日)

1)	<u>Yutaka Ogawa</u>	Yutaka OGAWA
2)	<u>Kazutomo Ogura</u>	Kazutomo OGURA
3)	<u>Naofumi Satou</u>	Naofumi SATOU
4)	<u>Kiyotada Funane</u>	Kiyotada FUNANE
5)	_____	
6)	_____	
7)	_____	
8)	_____	
9)	_____	
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